



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL31B225KAHNFNE
- Description : CAP, 2.2µF, 25V, ±10%, X7R, 1206

A. Samsung Part Number

			<u>CL</u>	<u>31</u>	<u>B</u>	<u>225</u>	<u>K</u>	<u>A</u>	<u>H</u>	<u>N</u>	E	<u>N</u>	E	
			1	2	3	4	5	6	1	8	9	10	1	
1	Series	Samsur	ng Multi	-layer	Cera	amic C	apa	citor						
2	Size	1206	(inch c	ode)		L:	3.2	± 0.2	2	mm		W:	1.6 ± 0.2	mm
3	Dielectric	X7R					(8)	Inne	r ele	ctroc	le		Ni	
4	Capacitance	2.2	μF					Tern	ninat	tion			Cu	
5	Capacitance	±10	%					Plati	ng				Sn 100%	(Pb Free)
	tolerance						9	Proc	luct				Product for F	POWER application
6	Rated Voltage	25	V				10	Spee	cial				Reserved for	r future use
\bigcirc	Thickness	1.6	± 0.2	mm			1	Pack	cagir	ng			Embossed T	ype, 7" reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1\therefore ±10% 1.0±0.2Vrms						
Tan δ (DF)	0.035 max.							
Insulation	10,000Mohm or 500Mohm· <i>µ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	250% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	X7R							
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±15%)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120 ℃ for 10~30sec.)						
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5°C, 10±1sec.						
Soldering heat	Tan δ, IR : initial spec.							

	Performance	Test condition					
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm					
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)					
		2hours \times 3 direction (x, y, z)					
Moisture	Capacitance change : within ±12.5%	With rated voltage					
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs					
	IR : 500Mohm or 25Mohm · μF						
	Whichever is Smaller						
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage					
Resistance	Tan δ : 0.05 max	Max. operating temperature					
	IR : 1000Mohm or 50Mohm $\cdot \mu F$						
	Whichever is Smaller	1000+48/-0hrs					
Temperature	Capacitance change : within ±7.5%	1 cycle condition					
Cycling	Tan δ, IR : initial spec.	Min. operating temperature \rightarrow 25 °C					
		\rightarrow Max. operating temperature \rightarrow 25 °C					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.